ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES*	l Composition De ht 2005. IPC, Bannock al and Pan-American c	claration burn, Illinois. A opyright conver	Il rights reserved untions.	under both	This docume level parts, th	ent is a declarati he declaration e	on of the subst ncompasses all	ances within th lower level m	e manufacture aterials for wh	er listed item	. Note: if ifacturer	the item is an as has engineering	sembly with low responsibility.
(5)_)	-21.1 IPC Web Site for Information on IPC-1752 Standard Form Type Distribute						Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information						
upplier Information													
ompany name*		Company un	ique ID		l	Unique ID Auth	ority			Response D	ate*		
nsemi										2024-05-16			
ontact Name	Title - Conta	ct	Phone - Contact* Email - Contact*				act*						
Product-Env-Stewards	Product Enviro Compliance				NA			Product-Env-Stewards@onsemi.com					
uthorized Representative*	Title - Repres	- Representative Phone - Representative* Email - Represent			presentative*								
roduct-Env-Stewards	Product Envi	ro Compliance			NA Product-Env-Stewards@onsemi.com				m				
Requester Item Number Mfr Iter		n Number	Number Mfr Item Name			Effective Date	Version	Manufact	Manufacturing Site		ght*	UOM	Unit Type
	NVH82	NVH820S75L4SPC Automotive 750 Module		V, 820A SSDC F	Power	2024-05-16 CNG			696	191.9	mg	Each	
Ianufacturing Proccess I	nformation												
Terminal Plating / Grid Array Material Ter		Ferminal Base A	Alloy	J-STD-020 MSL Ratin		Peak Process Body Temperature Max		erature Max	Time at Peak '	Temperature	Numbe	er of Reflow Cyc	les
Matte Tin (Sn) - anne	aled	CU Alloy		NA		0	C	30		seconds	3		
omments													
or more information regarding	material composition	please refer to	page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		nium (Cr6+), Polybro	ominated Biphenyls (PBB), Polybron	dmium and quantity limit of 0.1% by mass (100 minated Diphenyl Ethers (PBDE), and Bis(2-eth						
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of					
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the					
Supplier Digital Signature Ra	stislav Drska	Le								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Case	82300.0	mg	Supplier	Fiber Glass (SiO2)	65997-17-3		24690.002	mg
		-	Supplier	Poly(ButyleneTerephthalate)	30965-26-5		23044	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		2880.5	mg
			Supplier	PBT	26062-94-2		23044	mg
			-	Carbonic Dichloride	94334-64-2		8641.5	mg
Cover	26500.0	mg	Supplier	Fiber Glass (SiO2)	65997-17-3		7950.0005	mg
			Supplier	Poly(ButyleneTerephthalate)	30965-26-5		7420	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		927.5	mg
			Supplier	PBT	26062-94-2		7420	mg
			-	Carbonic Dichloride	94334-64-2		2782.5	mg
DBC	46100.0	mg	Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		19223.6992	mg
			В	Nickel (Ni)	7440-02-0		92.2	mg
			Supplier	Copper (Cu)	7440-50-8		26784.0996	mg
Die	1.3	mg	Supplier	Silicon (Si)	7440-21-3		1.3	mg
Die Attach Solder	2000.0	mg	Supplier	Dimethyl phthalate	131-11-3		20	mg
			Supplier	Amines	61788-95-2		20	mg
			Supplier	Isotridecan-1-ol	27458-92-0		20	mg
			Supplier	Silver (Ag)	7440-22-4		80	mg
			Supplier	Tin (Sn)	7440-31-5		1860	mg
Glue	585.0	mg	Supplier	2,3-epoxypropyl-trimethoxysilan	2530-83-8		58.5	mg
			Supplier	Miscellaneous	Trade Secret		58.5	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		468	mg
Plating	65.0	mg	Supplier	Tin (Sn)	7440-31-5		32.5	mg
			В	Nickel (Ni)	7440-02-0		32.5	mg
Screw	2960.0	mg	Supplier	Sulfur (S)	7704-34-9		1.184	mg
			Supplier	Carbon (C)	7440-44-0		14.8	mg
			Supplier	Manganese (Mn)	7439-96-5		26.64	mg
			Supplier	Silicon (Si)	7440-21-3		14.8	mg
			Supplier	Iron (Fe)	7439-89-6		2901.3921	mg
			Supplier	Phosphorus (P)	7723-14-0		1.1838	mg
Silicone Gel	31360.0	mg	Supplier	Silicone	70900-21-9		2979.2	mg
			Supplier	Hexamethyldisilazane	68909-20-6		156.8	mg

			Supplier	Dimethyl Siloxane	68083-19-2	28224	mg
Solder preform	16700.0	mg	Supplier	Silver (Ag)	7440-22-4	534.4	mg
			Supplier	Tin (Sn)	7440-31-5	15130.1992	mg
			В	Antimony (Sb)	7440-36-0	918.5	mg
			Supplier	Copper (Cu)	7440-50-8	116.9	mg
Terminal	2500.0	mg	Supplier	Silicon (Si)	7440-21-3	6.75	mg
			В	Nickel (Ni)	7440-02-0	33.75	mg
			Supplier	Copper (Cu)	7440-50-8	2458.875	mg
			Supplier	Phosphorus (P)	7723-14-0	0.625	mg
Terminal Holder	485000.0	mg	Supplier	Silver (Ag)	7440-22-4	145.5	mg
			Supplier	Copper (Cu)	7440-50-8	484854.5	mg
Thermistor	120.0	mg	Supplier	Tin (Sn)	7440-31-5	1.5	mg
			Supplier	Nickel Oxide (NiO)	1313-99-1	0.18	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4	0.192	mg
			В	Nickel (Ni)	7440-02-0	28.02	mg
			Supplier	Gold (Au)	7440-57-5	0.024	mg
			Supplier	Iron (Fe)	7439-89-6	30	mg
			А	Lead Oxide (PbO)	1317-36-8	27.504	mg
			Supplier	Cobalt Oxide (Co3O4)	1308-06-1	0.18	mg
			Supplier	Manganese Tetraoxide (Mn3O4)	1317-35-7	0.18	mg
			Supplier	Potassium Monoxide (K2O)	12136-45-7	12136-45-7 2.328	
			Supplier	Copper (Cu)	7440-50-8	13.26	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7	16.632	mg
Wire Bond - Al	0.6	mg	Supplier	Aluminum (Al)	7429-90-5	0.6	mg